



US 20220353994A1

(19) **United States**

(12) **Patent Application Publication**  
**Lin**

(10) **Pub. No.: US 2022/0353994 A1**

(43) **Pub. Date: Nov. 3, 2022**

(54) **ELECTRONIC MODULE**

**Publication Classification**

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(51) **Int. Cl.**  
**H05K 1/18** (2006.01)  
**H05K 3/28** (2006.01)

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(52) **U.S. Cl.**  
CPC ..... **H05K 1/18** (2013.01); **H05K 3/284** (2013.01); **H05K 2201/10037** (2013.01)

(21) Appl. No.: **17/731,267**

(22) Filed: **Apr. 28, 2022**

(57) **ABSTRACT**

An electronic module comprising electrical components on a circuit board and a molding body disposed on the circuit board to encapsulate the electrical components, wherein a recess is formed in the molding body for exposing an electrode of the electronic module for connecting with an external component.

**Related U.S. Application Data**

(60) Provisional application No. 63/180,659, filed on Apr. 28, 2021.

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